

We claim:

1. An adhesive composition for bonding a semiconductor chip to an attachment member for the chip comprising a curable polymer composition comprising from 1 to 900 weight-ppm spherical filler having an average particle size of from 10 to 100 μm and a major axis-to-minor axis ratio of from 1 to 1.5.
2. The adhesive composition of Claim 1, where the spherical filler has a particle size distribution with a standard deviation that does not exceed 10% of the average particle size of the filler.
3. The adhesive composition of Claim 1, where the curable polymer composition comprises from 1 weight-ppm to 700 weight-ppm spherical filler.
4. The adhesive composition of Claim 1, where the spherical filler is an inorganic spherical filler.
5. The adhesive composition of Claim 1, where the curable polymer composition is a curable silicone composition.
6. The adhesive composition of Claim 1, where the curable polymer composition is a curable epoxy resin composition.

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7. The adhesive composition of Claim 1, where the spherical filler has a major axis-to-minor axis ratio of from 1.0 to 1.1.

8. The adhesive composition of Claim 1, where the curable polymer composition is an addition reaction-curable silicone composition.

9. The adhesive composition of Claim 1 further comprising a thixotropic agent selected from the group consisting of organic resin powder, metal powder, and inorganic powder where the thixotropic agent has an average particle size of 100 μm or less and a specific surface area of 50 to 500 m^2/g .

10. A semiconductor device comprising a semiconductor chip bonded to an attachment member for the chip by an adhesive composition comprising from 1 to 900 weight-ppm spherical filler having an average particle size of from 10 to 100 μm and a major axis-to-minor axis ratio of from 1 to 1.5.

11. The semiconductor device according to Claim 10, where the spherical filler has a particle size distribution with a standard deviation that does not exceed 10% of the average particle size of the filler.

12. The semiconductor device according to Claim 10, where the curable polymer composition comprises from 1 weight-ppm to 700 with-ppm spherical filler.

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13. The semiconductor device according to Claim 10, where the spherical filler is an inorganic spherical filler.

14. The semiconductor device according to Claim 10, where the curable polymer composition is a curable silicone composition.

15. The semiconductor device according to Claim 10, where the curable polymer composition is a curable epoxy resin composition.

16. The semiconductor device according to Claim 10, where the spherical filler has a major axis-to-minor axis ratio of from 1.0 to 1.1.

17. The semiconductor device according to Claim 10, where the curable polymer composition is an addition reaction-curable silicone composition.

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